Conduct-O-Bond ECS2000

Technical Data Sheet

Conduct-o-Bond ECS2000

Electrically Conductive Adhesive

Conduct-o-Bond 2000 is a one part, silicone base, electrically conductive adhesive containing micron sized Nickel Coated Graphite particles as the conducting and shielding media. ECS Conduct-o-Bond 2000 is a room temperature



vulcanizing (RTV) and sealing material that cures in the presence of atmospheric moisture. This adhesive is specially formulated with a high quality non-corrosive silicone material that meets the requirements of MIL-A-46146, and will form a cured skin within 60 minutes after exposure to atmospheric moisture without the formation of corrosive by products. This material will remain flexible and conductive and can be used in environments where temperatures range from -60 to +350° F without degradation of physical or electrical properties. ECS Conduct-o-Bond 2000 is a thixotropic paste that can be applied to vertical surfaces without sagging. ECS Conduct-o-Bond 2000 can be used for form-in-place conductive gasketing to attach shielding windows to frames or bezels, bonding conductive elastomer gaskets, and for providing

Elastomer Adhesive	Silicone
Filler Material:	Nickel Coated Graphite
Color:	Dark Grev

Specific Gravity (+/-0.25)		2.010	ASTM D792
Hardness (Shore A) (+/-	7)	65	ASTM D2240
Tensile Strength (PSI)	Min.	500	ASTM D412
Elongation (%)	Min.	100	ASTM D412
	Max.	300	
Peel Strength (PPI)	Min.	4.0	ASTM D1876
Lap Shear (PSI)	Min.	130	ASTM D1002
Upper Operating Temp. (⁰ F)	Max.	+350	
Lower Operating Temp (⁰ F)	Min.	-60	ASTM D1329
Compression Deflection (%)	Min.	2.5	ASTM D575
Tack Free	Min.	60	
Light Handling	Hrs.	12-24	
Full Cure	Hrs.	96-144	
Volume Resistivity, Ohm/cm	Max.	.100	MIL-DTL-83528 Para. 4.6.11
Shelf Life, From Date Of Shipment In Original Closed Container	Months	6	

Conduct-O-Bond ECS5000

Technical Data Sheet

Conduct-o-Bond ECS5000

Electrically Conductive Adhesive

Conduct-o-Bond 5000 is a one part, silicone elastomer base, electrically conductive adhesive containing micron



sized Silver Plated Aluminum particles as the conducting and shielding media. **ECS Conduct-o-Bond 5000** is a room temperature vulcanizing (RTV) and sealing material that cures in the presence of atmospheric moisture. This adhesive is specially formulated with a high quality non-corrosive silicone material that meets the requirements of MIL-A-46146, and will form a cured skin within 60 minutes after exposure to atmospheric moisture without the formation of corrosive by-products. This material will remain flexible and conductive and can be used in environments where temperatures range from -60 to +350° F without degradation of physical or electrical properties. **ECS Conduct-o-Bond 5000** is a thixotropic paste that can be applied to vertical surfaces without sagging. **ECS Conduct-o-Bond 5000** can be used for form-in-place conductive gasketing to at-

tach shielding windows to frames or bezels, bonding conductive elastomer gaskets, and for providing EMI and envi-

ronmental protection as a sealant. ECS Conduct-o-Bond 5000 works especially well in harsh environments where corrosion is a concern. Also available with passivated silver

Elastomer Adhesive Silicone
ex- Filler Material: Silver Plated Aluminum
Color: Tan

aluminum particulars for tra corrosion protection.



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Specific Gravity (+/-0.25)		1.85	ASTM D792
Hardness (Shore A) (+/-7)		70	ASTM D2240
Tensile Strength (PSI)	Min.	260	ASTM D412
Elongation (%)	Min.	100	ASTM D412
Peel Strength (PPI)	Min.	4.0	ASTM D1876
Lap Shear (PSI)	Min.	175	ASTM D1002
Upper Operating Temp. (⁰ F)	Max.	+350	
Lower Operating Temp (⁰ F)	Min.	-60	ASTM D1329
Compression Deflection (%)	Min.	2.5	ASTM D575
Tack Free	Min.	60	
Light Handling	Hrs.	12-24	
Full Cure	Hrs.	96-144	
Volume Resistivity, Ohm/cm	Max.	.009	MIL-DTL-83528 Para. 4.6.10
Shelf Life, From Date Of Shipment In Original Closed Container	Months	6	

Performance of electrically conductive adhesives vary from one application to another. East Coast Shielding, Inc. cannot guarantee that the above specifications will be met in your application. If you need further assistance in evaluating your application, please do not hesitate to contact ECS for additional information.